2017 MARKETING PLANNER

AEROSPACE & DEFENSE TECHNOLOGY
The Engineer’s Guide to Design & Manufacturing Advances

AEROSPACE & DEFENSE TECHNOLOGY IS THE LARGEST-CIRCULATION MIL/AERO ENGINEERING MAGAZINE, SPANNING THE DEFENSE AND COMMERCIAL AEROSPACE MARKETS.

Targeted 100% to decision-makers who design/develop products for aerospace and defense applications.

Published 8x annually, Aerospace & Defense Technology reaches 70,000 Engineers and Managers.

New for 2017!

Aerospace Manufacturing & Fabrication – June and December 2017
A brand new supplement to Aerospace & Defense Technology, covering innovations in prototyping, 3D printing, and more.

Our Product Offerings include:

• An integrated toolbox to reach the defense/commercial/military aerospace design engineer through print, digital, e-mail, Webinars and Tech Talks, and social media.
• A dedicated RF and Microwave Technology section in each issue, covering wireless, power, test, materials, and more.

SPECIAL ISSUE:
Unmanned Vehicle & Robotics Technology — May 2017


Bonus Distribution: AUVSI’s Xponential 2017, Dallas, TX, May 8-11
BY JOB FUNCTIONS:

Aerospace & Defense Technology will connect your company to key product specifiers:

- Design Engineering: 46,440
- Engineering Management: 26,287
- R&D: 28,075
- Testing & Quality Control: 26,602
- Manufacturing & Production: 24,771

Aerospace & Defense Technology will reach new qualified buyers:

- Cameras/Video/Imaging: 21,266
- RF & Microwave Electronics: 19,805
- Board-Level Electronics/Embedded Systems: 24,531
- Connectors/Interconnects/Switches: 30,754
- ICs and Semiconductors: 23,575
- Electronic Components: 30,091
- Power Supplies/Batteries: 33,536
- Sensors/Transducers/Detectors: 29,611
- Data Acquisition: 38,932
- Test & Measurement Instruments: 33,204
- Software: 31,657
- Computers & Peripherals: 38,765
- Design/Analysis/Simulation Software: 25,777
- Motion Control/Positioning Equipment: 22,769
- Motors & Drives/Power Transmission: 23,407
- Board-Level Electronics/Embedded Systems: 23,575
- RF & Microwave Electronics: 24,531
- Sensors/Transducers/Detectors: 25,777
- Power Supplies/Batteries: 26,738
- ICs and Semiconductors: 26,789
- Electronic Components: 29,611
- Test & Measurement Instruments: 31,657
- Software: 38,765
- Computers & Peripherals: 38,932
- Design/Analysis/Simulation Software: 41,209
- Motion Control/Positioning Equipment: 45,664
- Motors & Drives/Power Transmission: 46,440

Your message in Aerospace & Defense Technology will reach new qualified buyers.

On average, 80% of our subscribers do not receive:

- COTS Journal: 91%
- Military & Aerospace Electronics: 75%
- Electronic Design: 74%

Source: Publisher’s own data, October 2016
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